

MEMS Innovation at Tohoku University



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Office of Cooperative
Research and Development

Tohoku University

JUNBA 2008, January 11, 2008



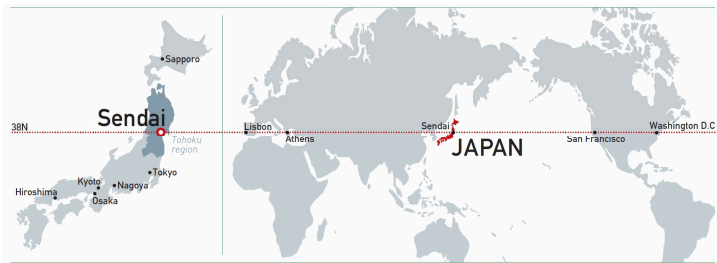
TOHOKU UNIVERSITY Sendai, Japan

The **100th** Anniversary of
Tohoku University in 2007

Tohoku University was founded in 1907
as the 3rd National University



TOHOKU UNIVERSITY Sendai, Japan



Nature, 2006

From Tokyo to Sendai: 96 min
Population of Sendai: 1 million
Result of popularity vote in 2004 :
1st: Sapporo, 2nd: Shizuoka, 3rd: Sendai, 4th: Tokyo



Bullet train "Shinkansen"



TOHOKU UNIVERSITY Sendai, Japan

Fundamental Policies

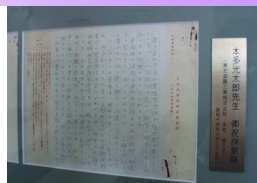
1. "Research-intensive University"
as its mission
2. "Have University's doors open to the
World and Community"
as its principle
3. "Development of Leading
Human Resources"
as its educational goal



TOHOKU UNIVERSITY Sendai, Japan

Major Research institutes with our tradition of "Practical Science"

- Institutes for Materials Research
– KS steel by Dr. Kotaro Honda
- Research Institute of Electrical Communication
– Yagi Antenna by Dr. Hidetsugu Yagi
- Semiconductor Research Institute,
Semiconductor Research Foundation
- Research Institute for Electric and Magnetic Materials



A congratulatory message on
the establishment of "Tohoku
Metal Industries Co., Ltd" by Dr.
Kotaro Honda

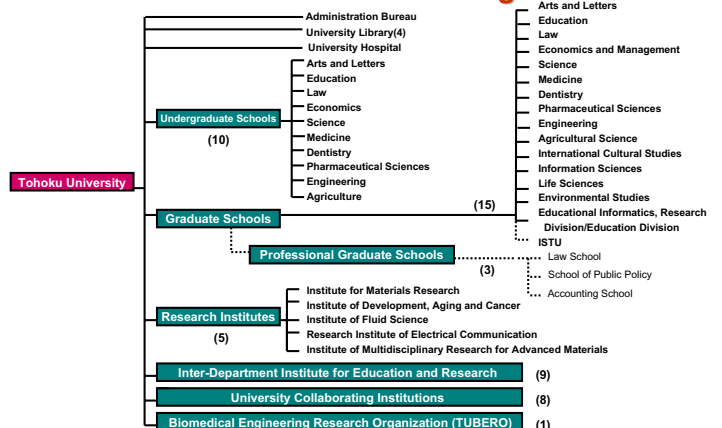
Forerunner of University Ventures before the Second World War

- Tohoku Metal Industries Co., Ltd.
(present: NEC TOKIN Corporation)
- Yagi Antenna Co., Ltd
(present: Hitachi Kokusai Electric Inc.)



Overview of TOHOKU UNIVERSITY

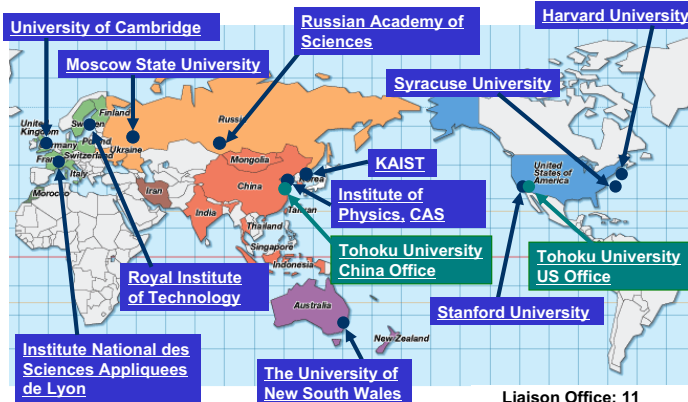
Research and Education Organization





Overview of TOHOKU UNIVERSITY

Liaison and Overseas Offices (As of July 2007)



Liaison Office: 11
Overseas Office: 2



Overview of TOHOKU UNIVERSITY

Tohoku University US office

- ◆ Supporting strategic application of research achievements to the world
- ◆ Supporting collaboration with overseas academia and international organizations (planning and holding symposium and seminar; developing collaborative researches and contract researches)
- ◆ Supporting cooperative educational opportunity with overseas academia and international organizations for symposium, distant learning, e-learning, short- and long-term overseas education
- ◆ Supporting Tohoku University Global Promotion Center
- ◆ Supporting formation of alumni organization in US and its activity

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Overview of TOHOKU UNIVERSITY

Research Paper Citations

National Ranking	International Ranking	Field	Citations	Papers
1	3	Materials Science	27,139	4,782
2	9	Physics	101,289	10,390
4	18	Chemistry	59,753	5,935
2	36	Engineering	11,448	3,173
6	66	All Fields	337,898	38,371

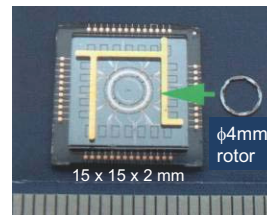
Resource: ISI Essential Science IndicatorsSM, January 1, 1997 – February 28, 2007

What's MEMS

MEMS: Micro Electro Mechanical Systems

Tiny system combining electrical and mechanical components

Small and high performance sensor and actuator



ex.) Gyroscope, TOKIMEC, Japan

2-axis angular velocity and
3-axis acceleration

Mechanical part
φ4mm silicon rotor

Electrical part
Electrostatic levitation control

rotation speed: 12,000 rpm

working as "the heart" or "the key" in a system

MEMS R&D at Tohoku Univ ~over 30 faculties~



MEMS products from Tohoku Univ-Industry collaboration



MEMS R&D facility at Tohoku University



120 m² MEMS clean room
400 users and 40 laboratories registered



Micro/Nanomachining Research and Education Center (MNC)
600 m² CMOS and MEMS clean room and evaluation facilities
500 users and 100 laboratories registered

2 cm x 2 cm, 2 and 4 inch facilities

More than 100 companies dispatched their researchers (full time)

National project on MEMS at Tohoku University

Special Coordination Funds for Promoting Science and Technology
supported by MEXT (Japanese Ministry of Education, Science, culture, sports)

Formation of Innovation Center for Fusion of Advanced Technologies on;

Tohoku University R&D Center of Excellence for Integrated Microsystems

Term: 2007~2016 (Max.)

Budget: ~\$70M

Concept

R&D center based on open innovation

- Next generation industry-university linkage system
- Human resource development beyond several fields

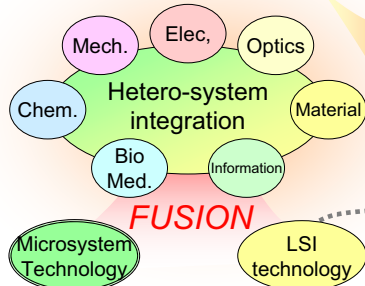
Innovation

Creative space for intelligent production

Safety space for automobile

- Seeds of next generation industry
- Integrated microsystem technology

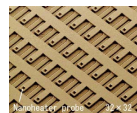
Required technology
Microsystem process for MEMS-LSI integration



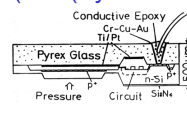
R&D Center of Excellence for Integrated Microsystems

(Formation of Innovation Center for Fusion of Advanced Technologies sponsored by Ministry of Education...) 2007~2009 (2016)

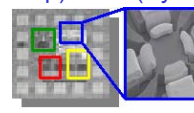
MEMS + LSI (SoC(System on Chip) & SiP(System in Package))



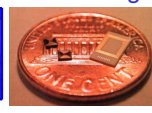
Arrayed MEMS,



Capacitive sensors,



RF integrated MEMS, Disposable devices

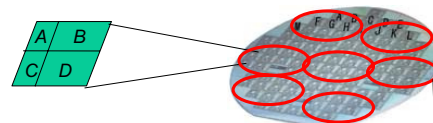
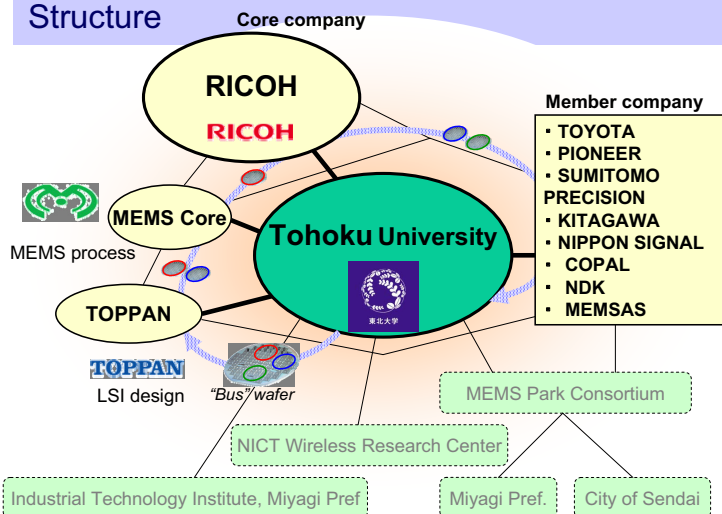


Realize MEMS having good mechanical property on advanced small feature size LSI

Problems to be solved :

- Low temperature processes (bonding or deposition) for MEMS having good mechanical properties for micromechanical resonator, switch etc..
- Damage-free and compatible processes (temperature, etching, electrostatic discharge etc.)
- Packaging, Test, Interconnection and so on.

Structure



Ricoh

Toyota motors

Pioneer

Nippon signal

Kitagawa machine works

Sumitomo precision

Nippon densa copal

Nippon denpa

MEMSAS

Tohoku Univ.

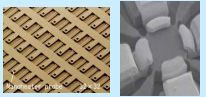
Shuttle service shared in project
(Toppan technical design center)

Low temperature additive MEMS process
(MEMS core)

Shuttle service shared in our project
+ Low temperature MEMS process

Next generation wireless system group

Esashi, Yamaguchi, Yugami, Tanaka, Ono
Toppa TDC, Pioneer, Nippon Denpa Kogyo, Ricoh, NICT



Multiprobe data storage On-chip filter

Wireless sensor, Ultra-Sensitive sensor group

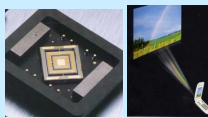
Miura, Kumano, Esashi, Ono, Tanaka, Nagasawa
Kitagawa, Sumitomo precision Product, Toyota motor, Nidec copal electronics



Wireless sensor for harsh environment

Optical microsystem group

Hane, Kanamori, Totsu, Kawai
Ricoh, Nippon signal



2D optical scanner Laser projector

BioMedical Microsystem group

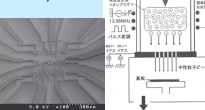
Matsue, Nishizawa, Abe, Haga
MEMSAS



Blood pressure sensor Biosensor

FabricationTest Equipment group

Samukawa, Miura, Yamaguchi, Ono, Kumano
Ricoh, MEMS



Parallel EB Neutral beam exposure system etching system

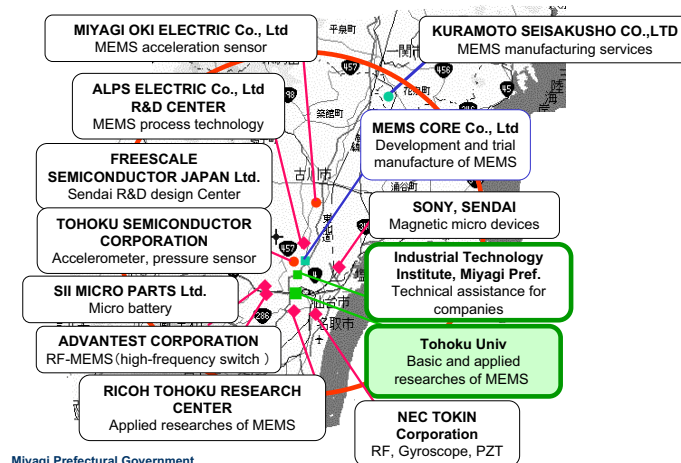
Technology Society System group

Ueyama, Kumano, Totsu, Takahashi



Industry-univ. collaboration system

MEMS activity in Sendai area

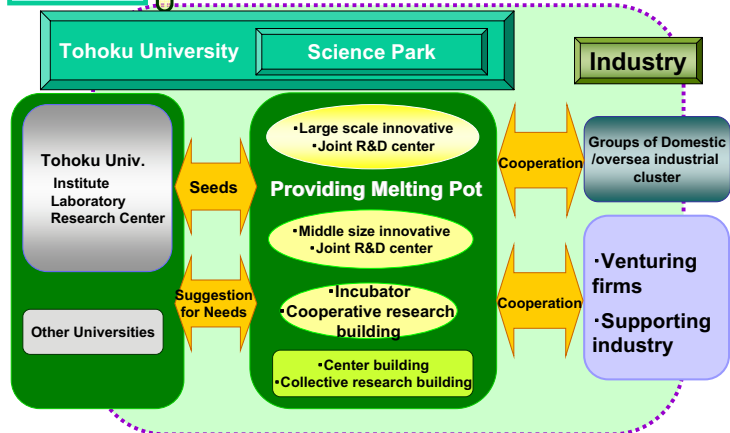


Miyagi Prefectural Government

University opened up to the region and the world

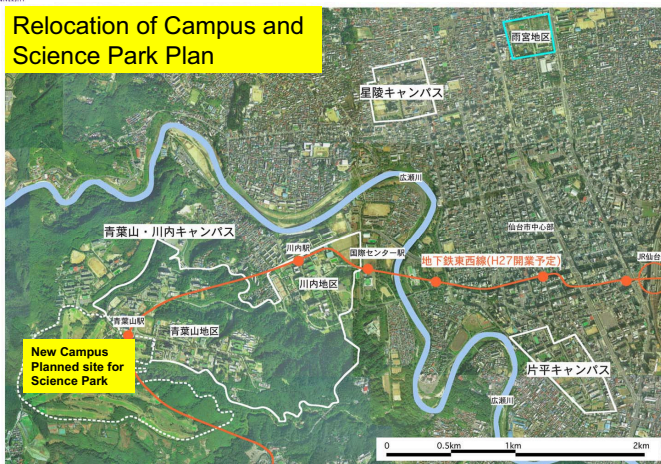
"Science Park" Plan

- Creation of new academic integration and integrated field of Industry-University-Government relations
- Bases for Personal exchange and for creation of new technology/industry



TOHOKU UNIVERSITY Sendai, Japan

Relocation of Campus and Science Park Plan



TOHOKU UNIVERSITY Sendai, Japan

New Aobayama campus framework plan (new campus in orange, existing campus in black)



Planning University's New Science Park

The Aobayama campus will be extended by some 81 hectares and part of the new site will be available for the science park.
As a start, Tohoku University hopes to entice about 50 companies to the park. It will provide various support infrastructures for the park's tenant companies, including access to existing research facilities at the university, and an opportunity to apply for public grants. Foreign companies are welcome!



Thank you for your attention!!



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